

# Unleashing Data Transmission: Next-level Probe Card for 112Gbps PAM4 Test Solution

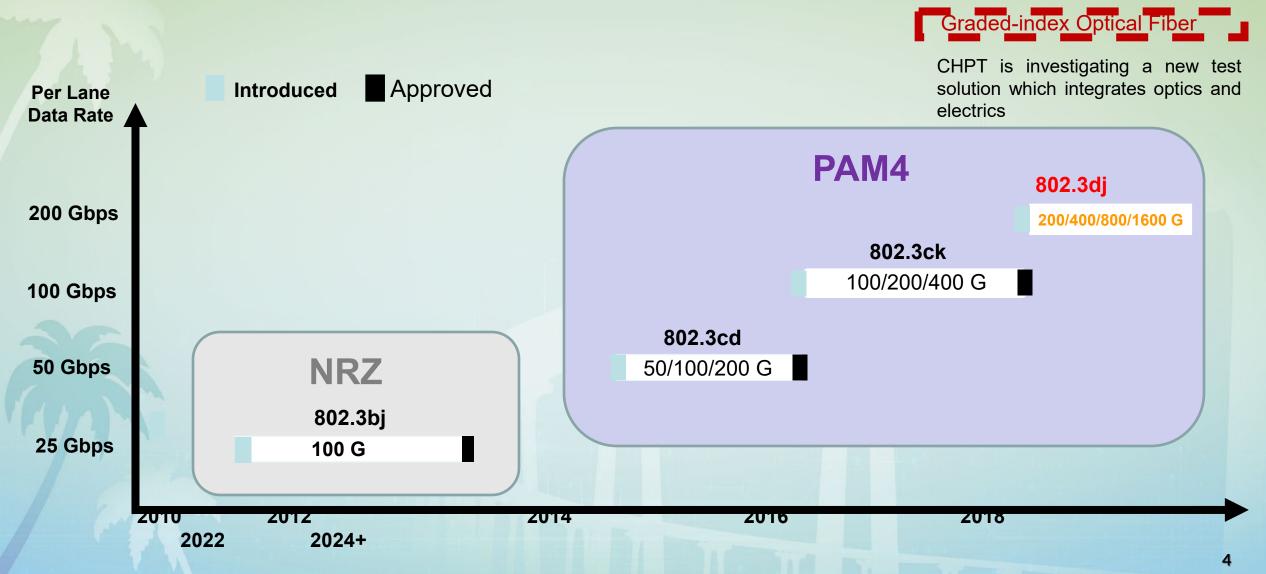


Johnson Tseng Matthew Lin

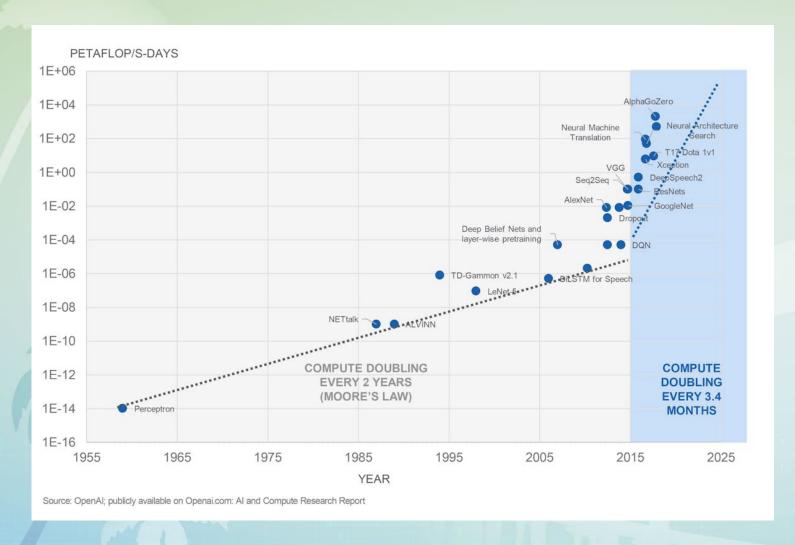
- **■**Data Transmission Trend
- **■CHPT Probe for high-speed PAM4 Test Solution**
- **Future Development**
- Summary

- **■**Data Transmission Trend
- **■CHPT Probe for high-speed PAM4 Test Solution**
- **Future Development** 
  - Summary

#### **IEEE 802.3** at Ethernet Rate

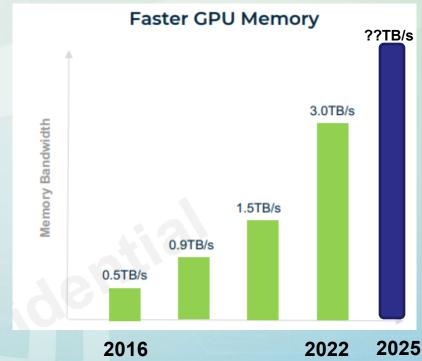


## Explosive growth in compute requirements for Al



PCle 4.0: 16Gbps PCle 5.0: 32Gbps

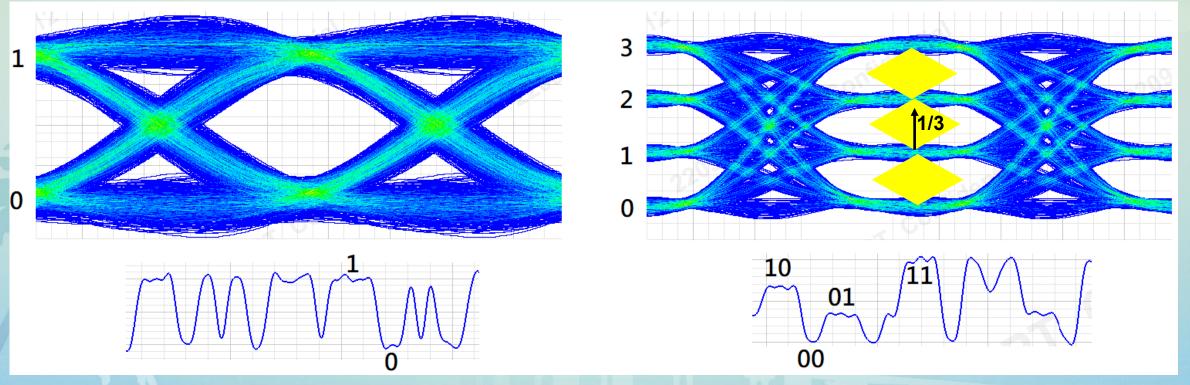
PCIe 6.0: 64Gbps PAM4 PCIe 7.0: 128Gbps PAM4



### **Modulation Methods: NRZ or PAM4**

| 112Gbps              | NRZ       | PAM4     |
|----------------------|-----------|----------|
| Baud Rate            | 112 GBaud | 56 GBaud |
| Nyquist<br>Frequency | 56 GHz    | 28 GHz   |
| Voltage level        | 2         | 4        |

- > Double Bit Rate : Higher efficiency for high-speed transmission
- ➤ Half symbol rate : Reduce signal loss
- ➤ Worse SNR : Eye height of PAM4 is approximately 33% of that for NRZ
- ➤ Higher BER : Smaller vertical eye opening (more sensitive to noise)

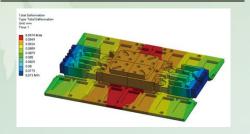


- **Data Transmission Trend**
- **■CHPT Probe for high-speed PAM4 Test Solution**
- **Future Development**

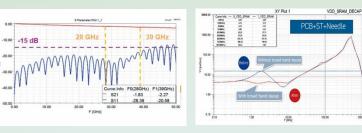
Summary

#### **CHPT All in House**

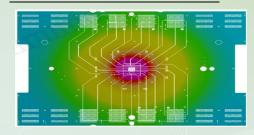
#### **Mechanical Simulation**



#### **SI/PI Simulation**



#### **Thermal Simulation**



CHPT
Al Design System
Probe Head 4.0

#### **PCB Capability**

- Up to 100 layers
- A/R 60
- Pitch 0.3mm
- Material: FR4, M6, M7, MW2000, MW4000

#### **Substrate Capability**

• Site: 20+

• C4 Count: 50,000 pins

C4 Pitch: 35um



#### **Probe Head**

• Min. Pitch: 35um

Max Pin Count: 50,000 pins

• -40~175 °C

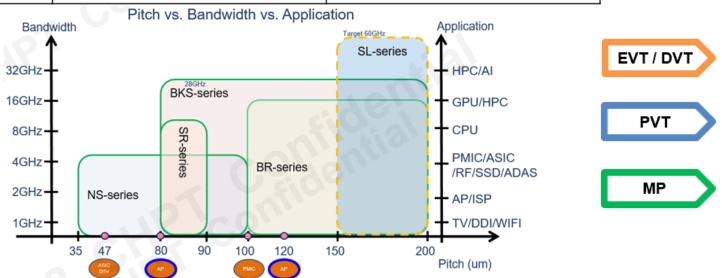


\* CHPT's technology has been patented or patent pending.

## Mix Needle Application

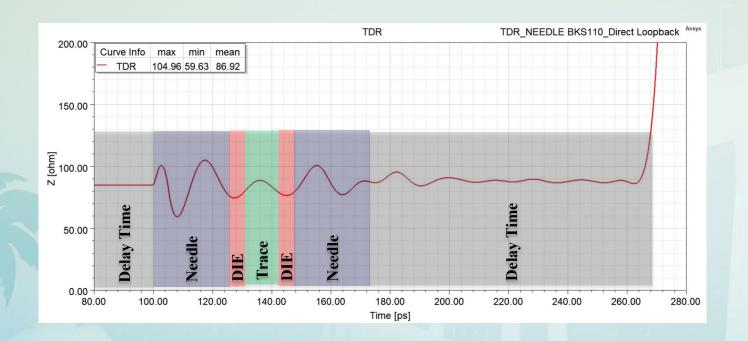
- 1. NS80 + BR120\_B(Flat) : Prevent burning needles by large current
- 2. BR120LF + BR155LF & BR120LF + BR160LF(Flat) → MP
- 3. BKS110 + BKS150(Flat) : 2024Q2/EVT
- 4. BKS110 + BKS200(Point) : 2024Q2/EVT
- 5. BKS90 + BKS180(Flat) : EVT Pass → MP
  - ◆ CHPT is dedicated to improve PCB/ST fabrication capability and develop various series of probe needles for different application.

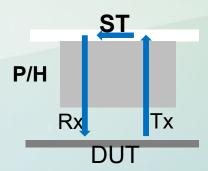
|           | Low Current Single needle < 1A [Force drop 20%] | High Current Single needle > 1A [Force drop 20%] |
|-----------|---|--|
| IP < 8GHz | ✓ NS  | ✓ SR   |
| IP > 8GHz | ✓ BR  | ✓ BR<br>✓ BKS                                    |



# **Current CHPT 112Gbps Solution**

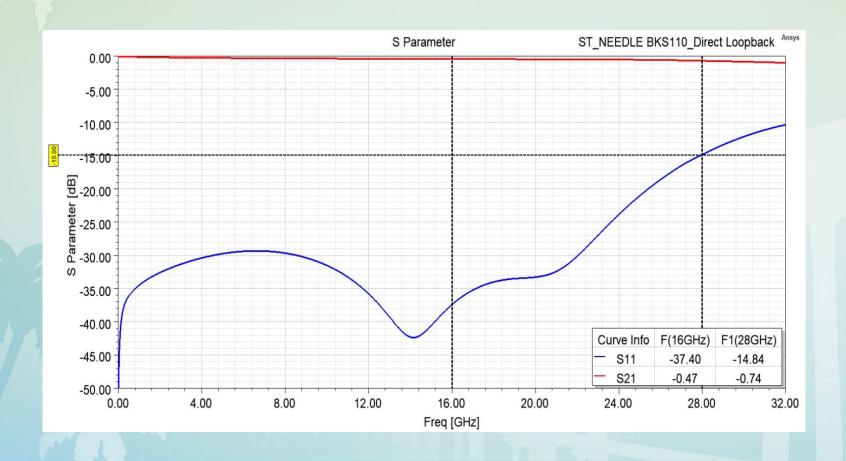
# **BKS Direct Loopback TDR 85 ohm impedance control**

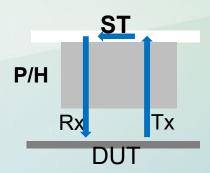




# **Current CHPT 112Gbps Solution**

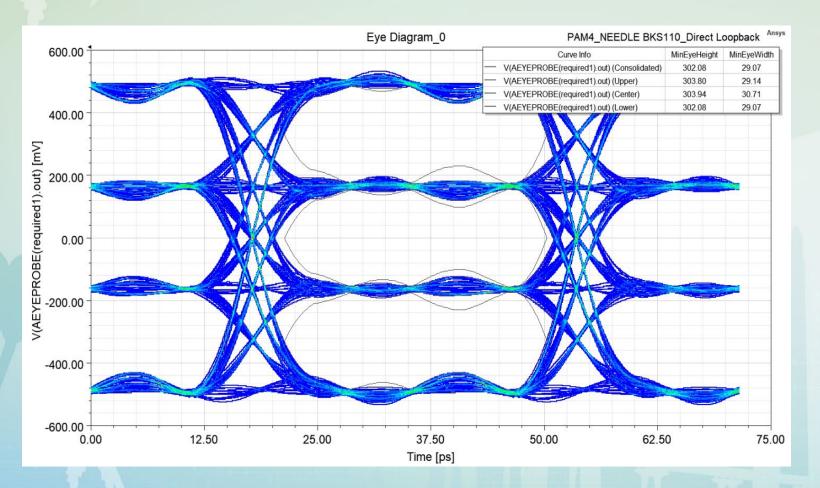
### **BKS Direct Loopback S Parameters**

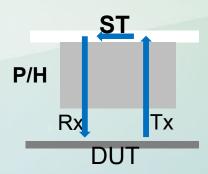




# **Current CHPT 112Gbps Solution**

#### **BKS Direct Loopback Eye Diagram**





- **■Data Transmission Trend**
- **■CHPT Probe for high-speed PAM4 Test Solution**
- **Future Development**
- **Summary**

## **Push For Higher Frequencies**

### 1. Tighter Impedance Control

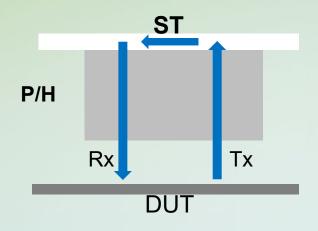
Not practical due to DIE pattern constraints on needle geometry

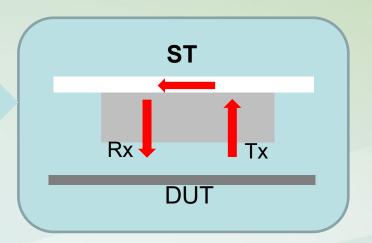
## 2. Shortening the Probe Needle ✓

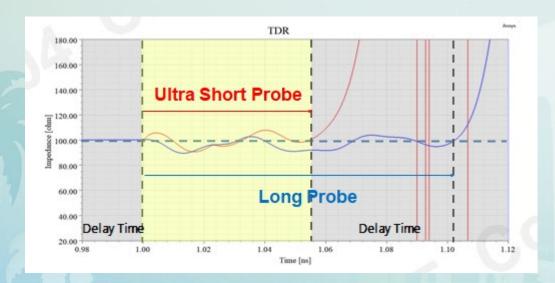
Based on idea of shrinking length to below 1/4 wavelength

#### **Evolution of Ultra Short Probe**

# **SL Needle**







- Shorter Total Signal Path
- ✓ Total Signal Trace is shorter than quarter wavelength
- √ Impedance control is less important
- Reduce Total Crosstalk Effect
- ✓ Reduce Noise sensitivity (PAM4)

# Significance of ¼ λ

#### Not enough rise time for return wave to significantly impact signal insertion

 $\Gamma = 0.5$ 

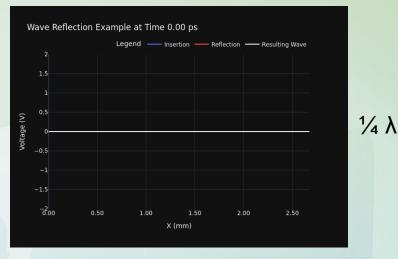
Target: 28 GHz for 112G PAM4

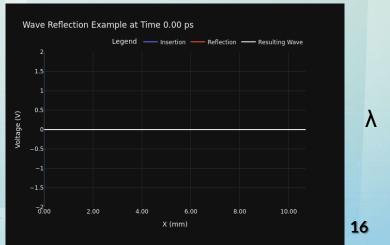
$$v = \frac{c}{\sqrt{\varepsilon_r \mu_r}}$$
  $\lambda = \frac{v}{\text{freq}}$ 

$$\lambda = \frac{c}{28 \text{ GHz}} \approx 10.7 \text{mm}$$

 $v = \frac{c}{\sqrt{\varepsilon_r \mu_r}}$   $\lambda = \frac{v}{\text{freq}}$  Assuming perfect dielectric (air) and conductor (copper) for relative magnetic permeability and relative permittivity. V ≈ C

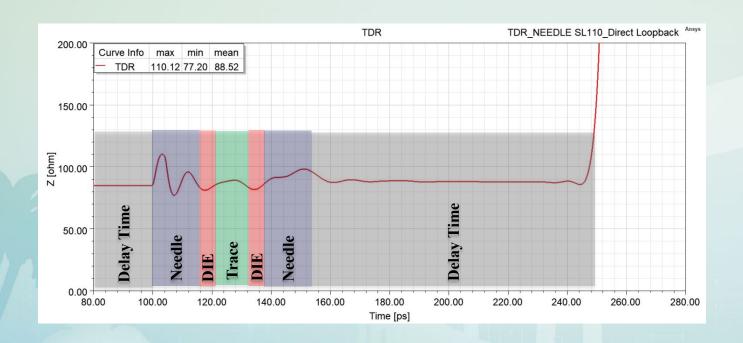
1/4 λ requires needle shorter than 2.67mm

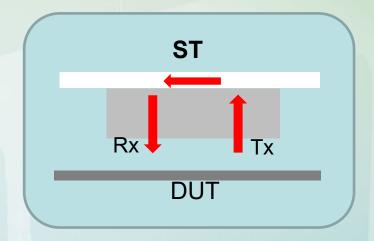




# **Future Product Development**

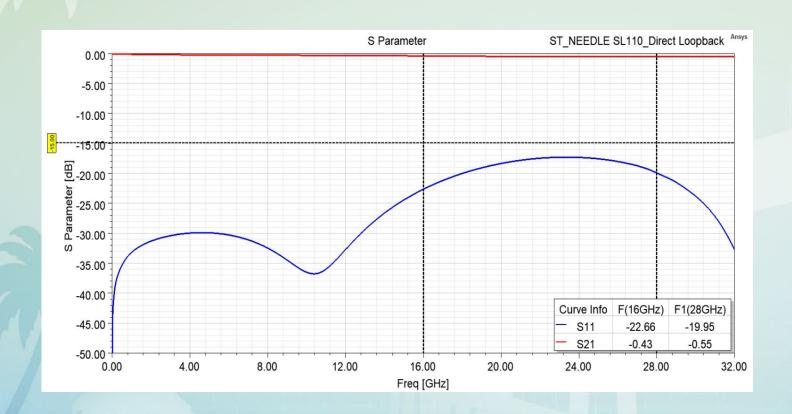
# SL Direct Loopback TDR 85 ohm impedance control

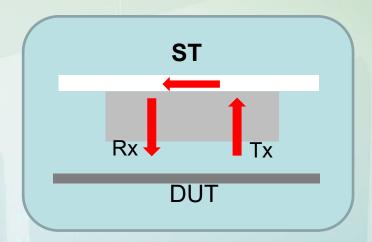




# **Future Product Development**

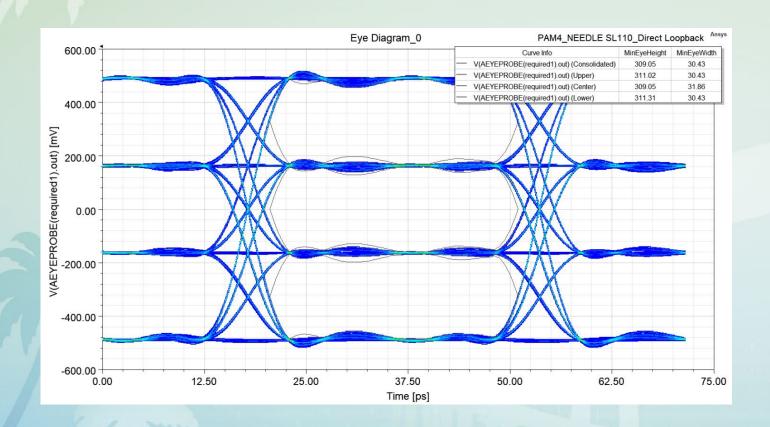
### SL Direct Loopback S Parameters

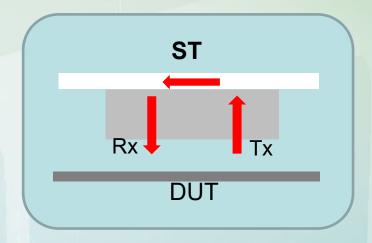




# **Future Product Development**

#### SL Direct Loopback Eye Diagram

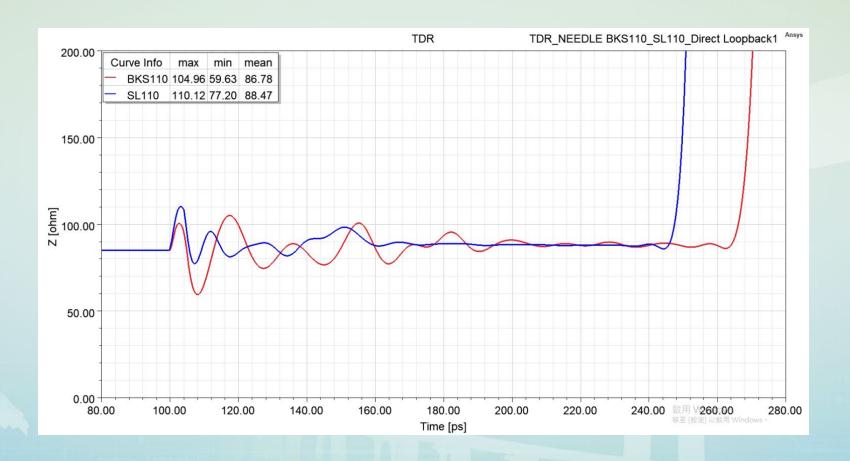




# **BKS and SL Comparison**

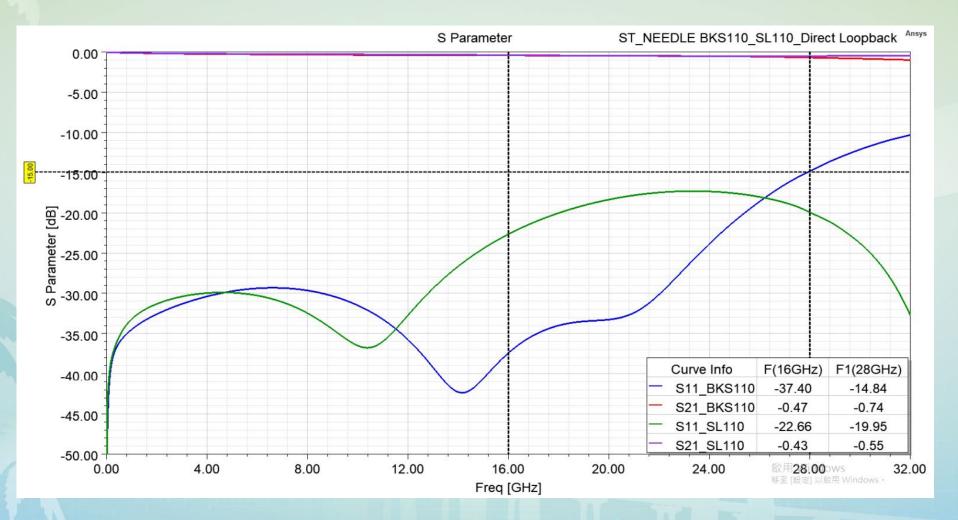
#### SL vs BKS Direct Loopback TDR

Rising Time: 4.16 ps



# **BKS and SL Comparison**

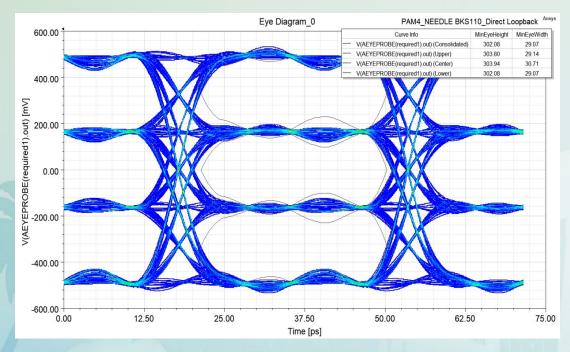
#### SL vs BKS Direct Loopback S Parameters



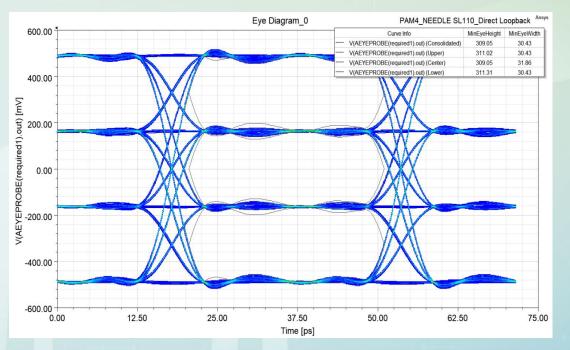
# **BKS and SL Comparison**

#### SL vs BKS Eye Diagram

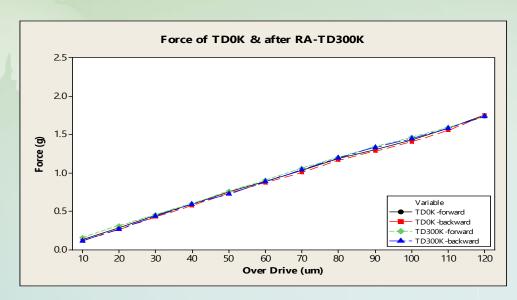
#### **BKS Series Needle**

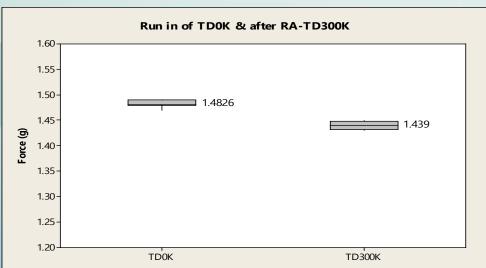


#### SL Series Needle



#### **CHPT High-Speed Probe Reliability Test**





> Test Temperature : 150 °C

➤ Touch Down Frequency : 2 TD/sec

➤ Touch Down: 300K

> The average force @ OD100 um decline 2.9% after 300K TD

|                              | CHPT High-Speed Probe |
|------------------------------|-----------------------|
| Minimum pitch [um]           | 150                   |
| Contact force(@ 4milsOT) [g] | 1.5 to 2.0            |
| Recommended O.D. [um]        | 30 to 100             |
| Max. O.D. [um]               | 120                   |
| Probe length [um]            | 1580(SL)              |
| Life time                    | 300K at least         |
| Temperature [°C]             | -40 / 150             |

- **Data Transmission Trend**
- **■CHPT Probe for high-speed PAM4 Test Solution**
- **Future Development**
- **■Summary**

## Summary

- > CHPT has successfully designed a probe for 112G PAM4 Test Solution
  - Deliver functional product to customer enabling high speed testing
- ➤ High quality and durability (The average force decline 2.9% after 300k touch down)
- > CHPT is developing an Ultra-short Probe (SL Needle) to exceed current compliance standard and prepare for future high-speed testing, even for 224Gbps
  - > Total signal path length < Quarter Wavelength
- > Ready to serve the needs of high speed testing in future automotive and HPC products